MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS
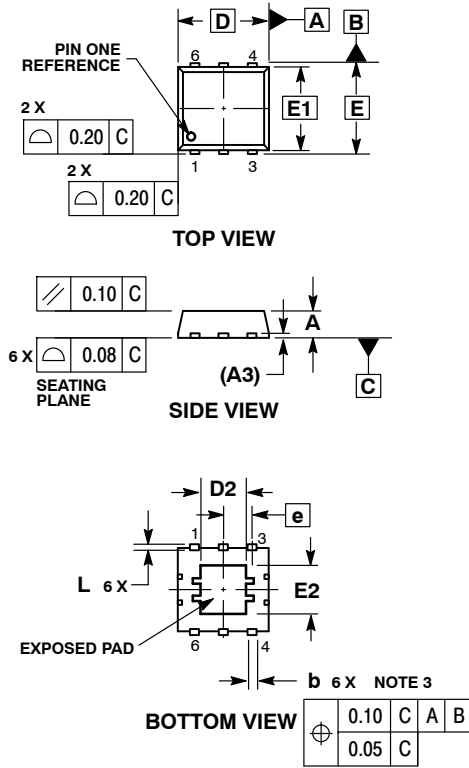
ON Semiconductor®

HSON−6
CASE 506AE−01
ISSUE A

DATE 26 JAN 2005

SCALE 2:1

TOP VIEW

PIN ONE REFERENCE

2 X △ 0.20 C

2 X △ 0.20 C

SIDE VIEW

⫽ 0.10 C

6 X △ 0.08 C

SEATING PLANE

(A3)

BOTTOM VIEW

D2

L 6 X

E2

EXPOSED PAD

b 6 X NOTE 3

⊕ 0.10 C A B
0.05 C

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.10 AND 0.15 MM FROM TERMINAL.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

DIM	MILLIMETERS	
	MIN	MAX
A	0.70	0.90
A3	0.15 REF	
b	0.20	0.40
D	2.90 BSC	
D2	1.40	1.60
E	3.00 BSC	
E1	2.80 BSC	
E2	1.50	1.70
e	0.95 BSC	
L	0.15	0.25

GENERIC MARKING DIAGRAM*

XXX
XYY
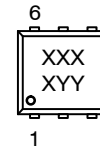
XXXX   = Specific Device Code
YY   = Wafer Lot

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, "G" or microdot " ▪", may or may not be present.

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DESCRIPTION:	HSON−6, 2.9 X 3.0 MM, 0.95 MM PITCH		PAGE 1 OF 1